

1A LED Driver with internal switch

Outline

- TTP932 is a high efficiency , constant current , continuous mode inductive step-down converter, designed for driving constant current to high power (single or multiple) LED with only 4 external components. TTP932 operates from input supply between 5V and 33V and provides an externally adjustable output current of up to 1A.
- The TTP932 is specifically designed with PFM control to enhance the efficiency up to 95%. The Output current can be modify by an external resister, and can adjusted, by applying an external control signal to the DIM pin, The DIM pin will accept a PWM waveform.

Additionally, to ensure the system reliability, TTP932 is built-in with over temperature protection, and LED open-circuit short-circuit protection to protect system from being damaged.

Characteristic

- 1A output current
- Wide input voltage range : 5V \sim 33V
- High efficiency (up to 95%)
- Internal NDMOS power switch
- Single pin on / off and brightness control using PWM
- Hysteretic PFM improves efficiency at light loads
- With Thermal
 Soft start
 LED open-short detect protection
- Only 4 External Components
- Up to 1Mhz switching frequency
- Typical 3% output current accuracy

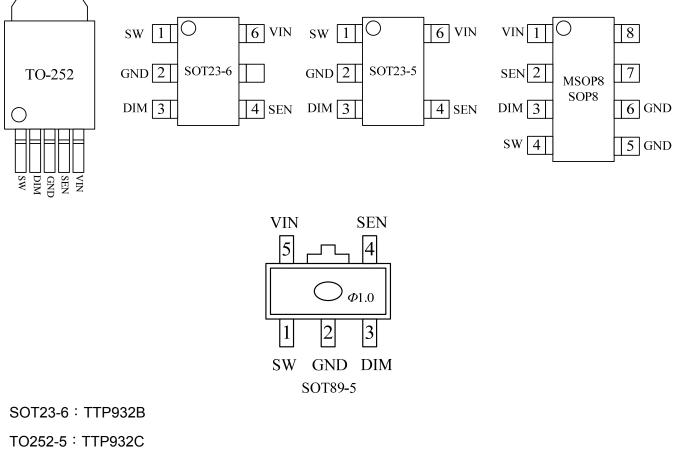
Applications

- High power LED lighting
- Automotive LED lighting
- Low voltage industrial lighting
- LED back-up lighting
- Constant Current Source



TTP932

Package type



MSOP8 (with Thermal Pad): TTP932D

SOP8 : TTP932E

SOT89-5 : TTP932F1

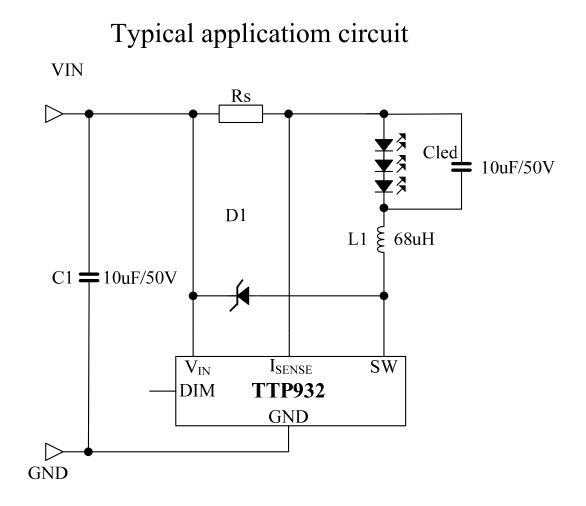
SOT23-5 : TTP932J

Pin Description

Pin name	Pin Description
SW	Drain of NDMOS switch
GND	Ground pad
DIM	Dimming control pad
ISEN	Connect resistor RS from this pin to VIN to define nominal average output current
VIN	Power pad



Application circuit





Electrical Characteristics

Absolute maximum ratings

	Parameter	Symbol	Rating	Unit
Supply Voltage		VIN	0-33(40V for 0.5 秒)	V
Output Current		IOUT	1.25	Α
Sustaining Volt	age at SW pin	VSW	-0.5~33(40V for 0.5 秒)	V
	SOP8		1.4	
	MSOP8 (thermal PAD)		1.45	
Power	TO252	PD PD	2.8	w
Dissipation *	SOT23-6		1.2	vv
	SOT23-5		1.2	
	SOT89-5		1.45	
	SOP8		89.3	
	MSOP8 (thermal PAD)		86.2	
Thermal	TO252		44.6	°C ///
Resistance	SOT23-6	Rth (j-a)	104.2	− °C <i>/</i> W
	SOT23-5		104.2	
	SOT89-5		86.2	
Operating Temperature		Тор	-40 °C - +85 °C	°C
Storage Temperature		Tsto	-55° C - +150° C	°C
Junction Temperature		Tj-MAX	150	°C
* 2 layer The PCB size is 22mm* 20mm				
** Power Dissipation depend on PCB layout				

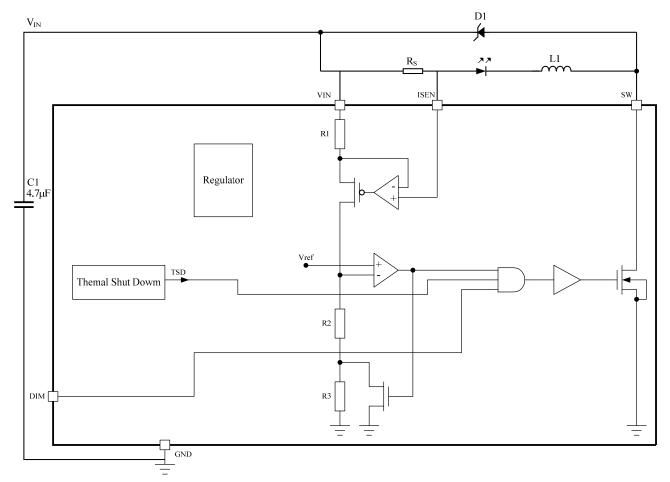
• DC / AC characteristics :

(Test condition : VIN=12V \cdot V_{OUT}=3.6V \cdot L1=68uH \cdot CIN=C_{OUT}=10uF \cdot Ta= 25 $^{\circ}$ C ; unless otherwise specified.)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Operating voltage	Vin		5	-	33	V
Operating current	lin	VIN= 5V~33V	-	1	2	mA
Output current	I _{OUT}		-	-	1	A
Output current Accuracy	$\Delta I_{OUT}/I_{OUT}$	$150mA \le I_{OUT} \le 1A$	-	±3	±5	%
Efficiency		V _{IN} =12V ∖ I _{OUT=} 350mA ∖ V _{out} =10.8V	-	95	-	%
SW Dropout voltage	ΔVsw	Ιουτ =1 Α	-	0.5	-	V
Internal propagation delay	TPD		100	200	300	NS
Input voltage	Vih		3.5	-	5	V
Input voltage	VIL		-	-	0.5	V
Sense threshold hysteresis	VSENSEHYS		-	±15	-	%
Mean current sense threshold voltage	VSENSE		95	100	105	Μv
Switch on resistance	RDS(ON)	V _{IN} =12V ∖ I _{OUT=} 350mA ∖ V _{out} =10.8V	-	0.5	1	Ω
Minimum switch 'ON' time	Tonmin		100	350	450	ns
Minimum switch 'OFF' time	TOFFmin		100	350	450	ns
Recommended duty cycle range oft switch	Dsw		0.2	-	0.8	-
Maximum operating frequency	Freqмах		40	-	1000	KHz
Thermal Shutdown Threshold	Tsd		145	160	175	°C
Thermal Shutdown Hystersis	Tsd-hys		-	20		°C
Duty cycle range of PWM signal applied to DIM pin	Duty _{DIM}	PWM frequency = 1KHz	0.01	-	1	-
Rise Time of Output current	Tr	Vout= 3.6V \ I _{OUT=} 350mA \ fblm=1kHz \ Dutyblm=50%	-	20	-	ns
Fall Time of Output current	Tf	Vо∪т= 3.6V ∖ I _{ОUT=} 350mA ∖ fpiм=1kHz ∖ Dutypiм=50%	-	20	-	ns



Block diagram



Device description

The device, in conjunction with the coil (L1) and current sense resistor (RS), forms a selfoscillating continuous-mode buck converter.

I. Device operation (Refer to block diagram and Figure 1 - Operating waveforms)

Operation can be best understood by assuming that the DIM pin of the device is unconnected and the voltage on this pin (VDIM) appears directly at the (+) input of the comparator.

When input voltage VIN is first applied, the initial current in L1 and RS is zero and there is no output from the current sense circuit. Under this condition, the (-) input to the comparator is at ground and its output is high. This turns MN on and switches the SW pin low, causing current to flow from VIN to ground, via RS, L1 and the LED (s). The current rises at a rate determined by VIN and L1 to produce a voltage ramp (VSENSE) across RS. The supply referred voltage VSENSE is forced across internal resistor R1 by the current sense circuit and produces a proportional current in internal resistors R2 and R3. This produces a ground referred rising voltage at the (-) input of the comparator. When this reaches the threshold voltage (Vref), the comparator output switches low and MN turns off. The comparator output also drives another NMOS switch, which bypasses internal resistor R3 to provide a controlled amount of hysteresis. The hysteresis is set by R3 to be nominally 15% of VADJ.

When MN is off, the current in L1 continues to flow via D1 and the LED (s) back to VIN. The current decays at a rate determined by the LED (s) and diode forward voltages to produce a falling voltage at the input of the comparator. When this voltage returns to VADJ, the comparator output switches high again. This cycle of events repeats, with the comparator input ramping between limits of Vref \pm 15%.

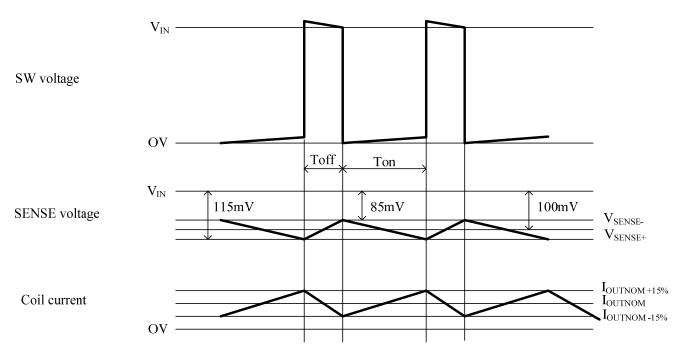


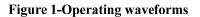
II. Switching thresholds

With VADJ = VREF, the ratios of R1, R2 and R3 define an average VSENSE switching threshold of 100mV (measured on the ISENSE pin with respect to VIN). The average output current IOUTnom is then defined by this voltage and RS according to \therefore

IOUTnom = 100mV/RS

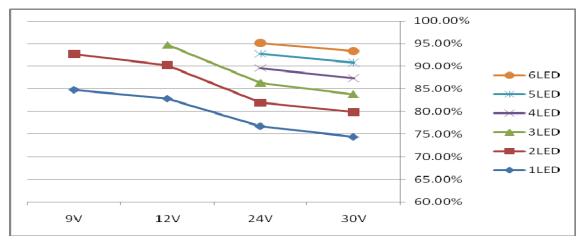
Nominal ripple current is ± 15 mV/RS





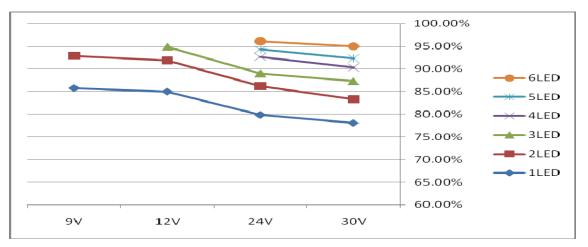
III. Typical Performance Characteristics

1. Efficiency vs. Input Voltage at Various LED Cascaded Number

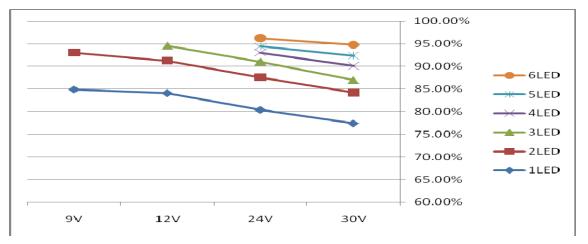


Efficiency vs. input voltage @L=22uH \ IOUT=370mA

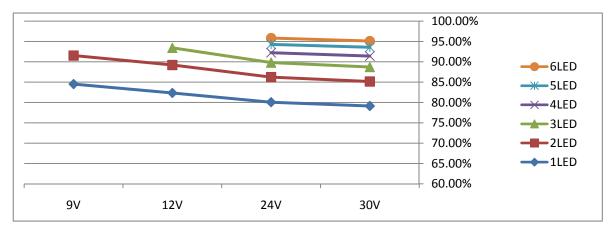




Efficiency vs. input voltage @L=68uH \ I_{OUT}=370mA



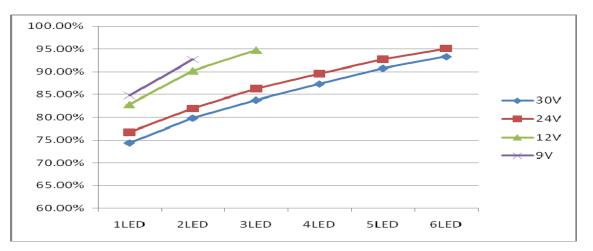
Efficiency vs. input voltage @L=100uH · I_{OUT}=370mA



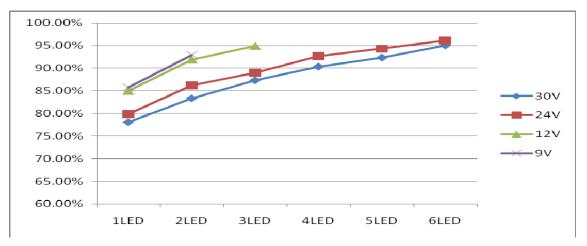
Efficiency vs. input voltage @L=68uH \ I_{OUT}=770mA



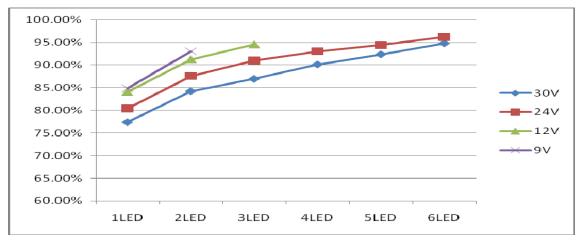
2. Efficiency vs. LED Cascaded Number at Various Input Voltage



Efficiency vs. LED cascaded number @L=22uH \ I_{OUT}=370mA

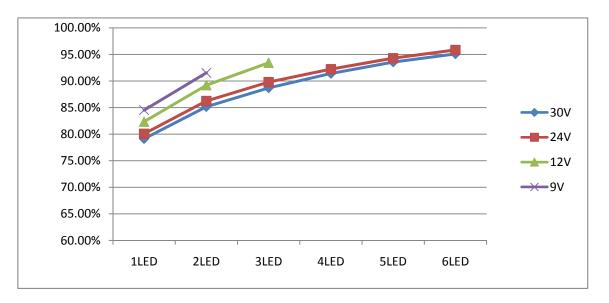


Efficiency vs. LED cascaded number @L=68uH \ I_{OUT}=370mA



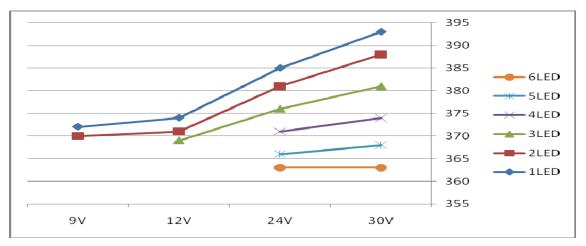
Efficiency vs. LED cascaded number @L=100uH \ I_{OUT}=370mA



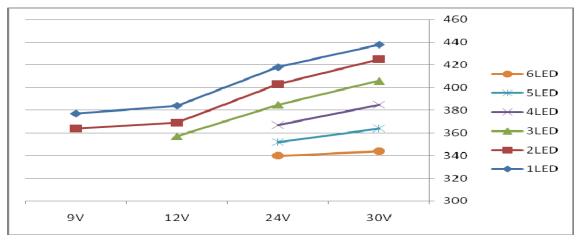


Efficiency vs. LED cascaded number @L=68uH \cdot I_{OUT}=770mA

3. Output Current vs. Input Voltage at Various LED Cascaded Number

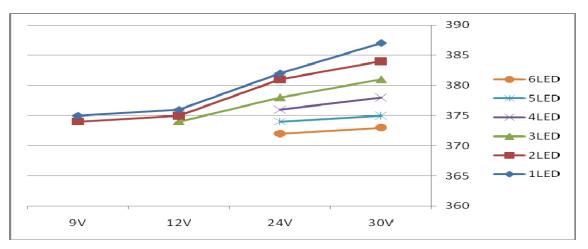


Output current vs. input voltage @L=22uH \ I_{OUT}=370mA

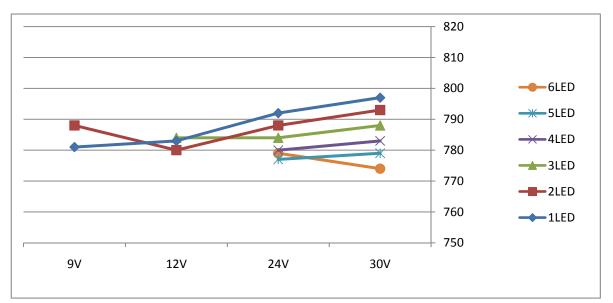


Output current vs. input voltage @L=68uH \ I_{OUT}=370mA

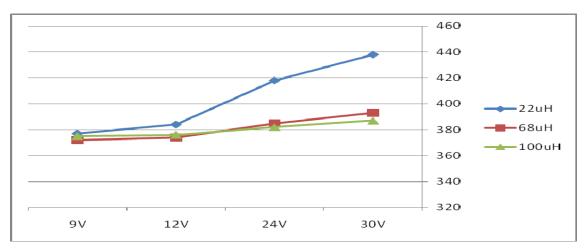




Output current vs. input voltage @L=100uH \smallsetminus I_{OUT}=370mA

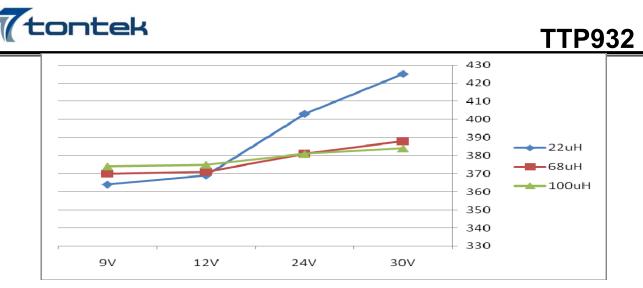


Output current vs. input voltage @L=68uH $\ I_{OUT}$ =770mA

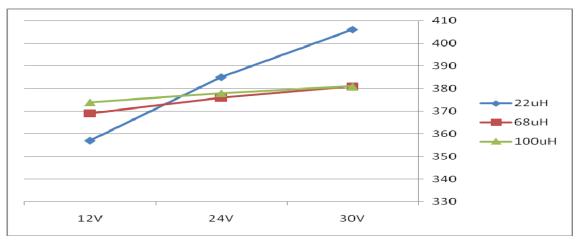


4. Output Currnet vs. Input Voltage at Various Inductor

Output current vs. input voltage @1-LED in cascaded, I_{OUT} =370mA

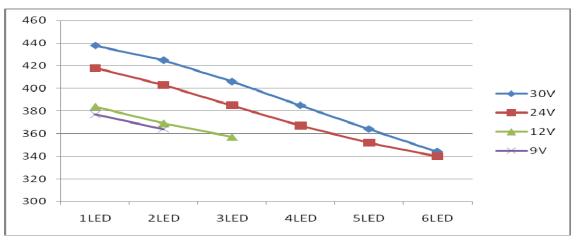








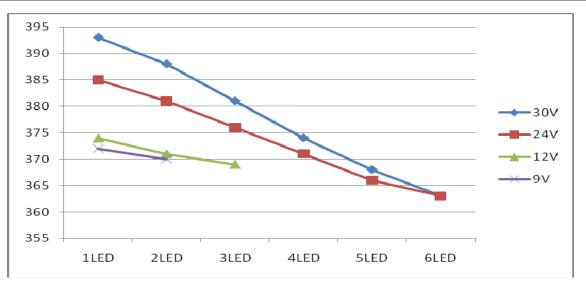
5. Output Current vs. LED Cascaded Number at Various Input Voltage



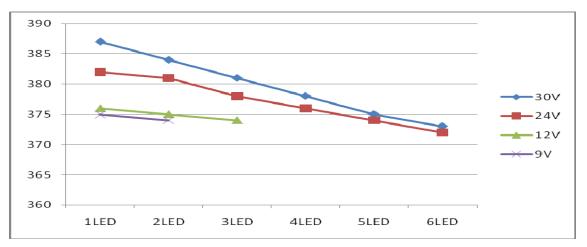
Output current vs. LED cascaded number @L=22uH \ I_{OUT}=370mA



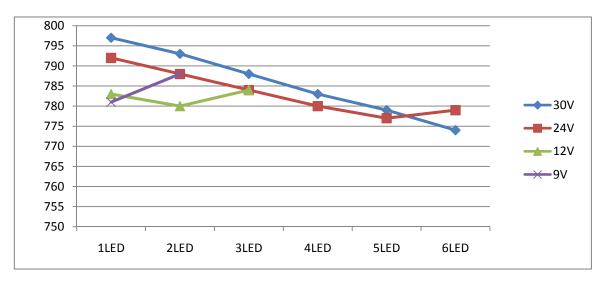
TTP932



Output current vs. LED cascaded number @L=68uH · I_{OUT}=370mA

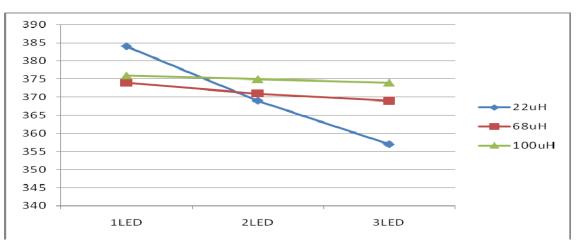


Output current vs. LED cascaded number @L=100uH \ I_{OUT}=370mA



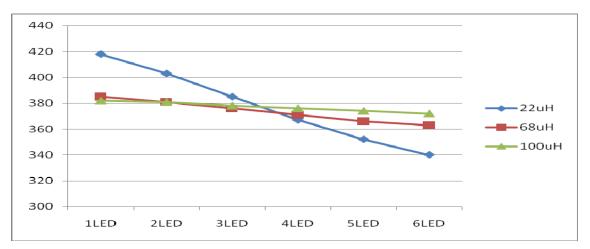
Output current vs. LED cascaded number @L=68uH \ I_{OUT}=770mA



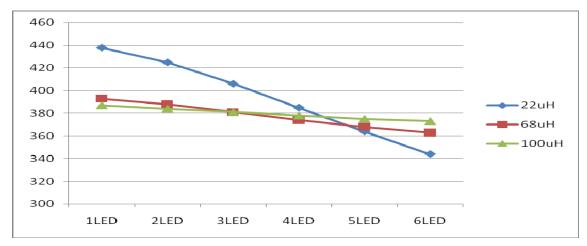


6. Output Current vs. LED Cascaded number at Various Inductor

Output Current vs. LED Cascaded number @VIN=12V \ I_{OUT}=370mA

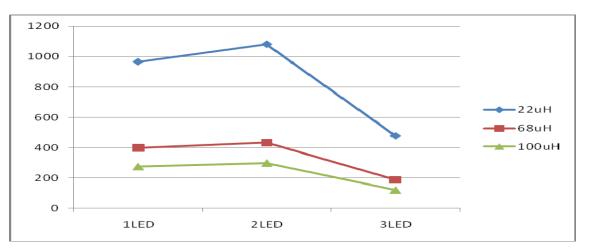


Output Current vs. LED Cascaded number @VIN=24V \ I_{OUT}=370mA



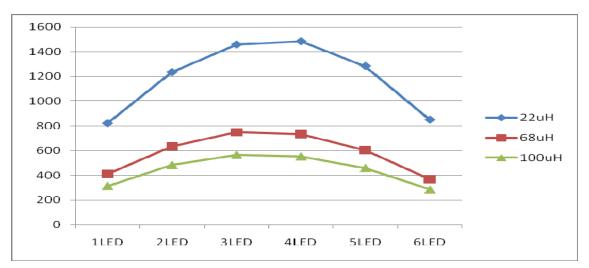
Output Current vs. LED Cascaded number @VIN=30V \ I_{OUT}=370mA

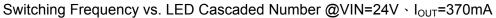


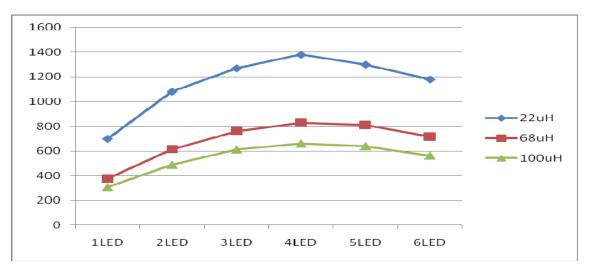


7. Switching Frequency vs. LED Cascaded Number at Various Inductor

Switching Frequency vs. LED Cascaded Number @VIN=12V \ I_{OUT}=370mA



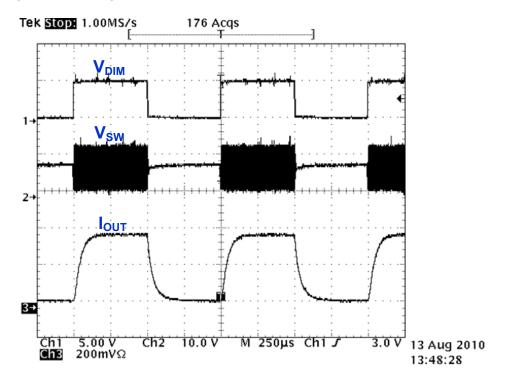




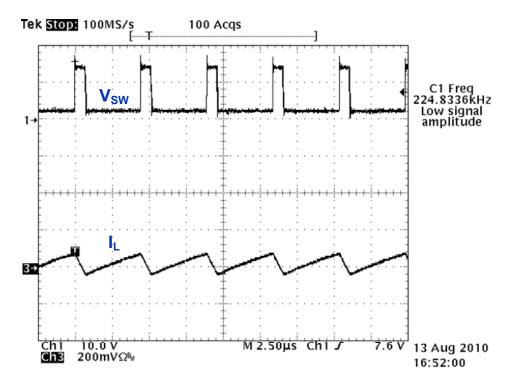
Switching Frequency vs. LED Cascaded Number @VIN=30V \ I_{OUT}=370mA



8. Dimming and switching waveforms



Dimming waveform ($V_{\text{IN}}\text{=}12V \mathrel{\scriptstyle{\searrow}} R_{\text{SEN}}\text{=}0.27\Omega \mathrel{\scriptstyle{\searrow}} 3\text{-LED}$)



Switching waveform ($V_{\text{IN}}\text{=}12V \mathrel{\scriptstyle{\curlyvee}} R_{\text{SEN}}\text{=}0.27\Omega \mathrel{\scriptstyle{\curlyvee}} 3\text{-LED} \,)$



IV. Application notes

Setting nominal average output current with external resistor RS

The nominal average output current in the LED(s) is determined by the value of the external current sense resistor (RS) connected between VIN and lout and is given by :

IOUTnom = 0.1/RS [for RS \geq 0.1 Ω]

Nominal ripple current is ± 15mV/RS

The table below gives values of nominal average output current for several preferred values of current setting resistor (RS) in the typical application circuit shown on page 1 :

RS (Ω)	Nominal average output current (mA)				
0.1	1000				
0.13	760				
0.15	667				

1. Dimming

A Pulse Width Modulated (PWM) signal with duty cycle DPWM can be applied to the DIM pin.

A logic low (below 0.5V) at DIM will disable the internal MOSFET and turn off the current Flow to the LED array . An internal pull-high circuit ensures that The TTP932 is ON when DIM pin is unconnected.

2. Open/short circuit LED protection

When any LED is open - circuit, the output current will be turned off.

When any LED is short - circuit, the output current will be limited to its preset value.

3. Over Temperature protection

When the junction temperature over range. TTP932 will turn off output Current.

4. Minimum Input Voltage

The Minimum Input Voltage is the sum of the voltage drops on RSEN , DCR of L1 ,

Rds (ON) of Internal MOS switch and the total forward voltage of LEDS VLED.

Vin=VRS+VLED+VL1+VSW



5. Design Consideration

Switching Frequency :

For better output current accuracy , the switching frequency should be determined by Minimum on/off time SW waveform.

Fsw=(1-D)/TOFF,MIN, when the duty cycle is large than 0.5 (D = Vout / Vin)

或 Fsw=D/Ton,min, when the duty cycle is smaller than 0.5

The switching frequency is related to efficiency (better at low frequency), the size \angle cost Of components, and the amplitude of output ripple voltage and current (smaller at high frequency).

The slower switching frequency comes from the large value of inductor. In many applications, the Sensitivity of EMI limits the switching frequency. The switching frequency can be ranged from 40Khz To 1.0Mhz.

LED Ripple Current :

A LED constant current driver, is designed to control the current through the cascaded LED, instead of the voltage across it. Higher LED ripple current allows the use of smaller inductance, smaller output capacitance and even without an output capacitor.

The advantages of higher LED ripple current are to minimize PCB size and reduce cost because of no output capacitor. Lower LED ripple current requires large induce and output capacitor.

The advantages of lower LED ripple Current are to extend LED life time and to reduce heating of LED. The recommended ripple current is From 5 % to 20% of normal LED output current.

6. Capacitor selection

A low ESR capacitor should be used for input decoupling, as the ESR of this capacitor appears in series with the supply source impedance and lowers overall efficiency. This capacitor has to supply the relatively high peak current to the coil and smooth the current ripple on the input supply.

A minimum value of 4.7uF is acceptable if the input source is close to the device, but higher values will improve performance at lower input voltages, especially when the source impedance is high. The input capacitor should be placed as close as possible to the IC.

For maximum stability over temperature and voltage, capacitors with X7R, X5R, or better dielectric are recommended. Capacitors with Y5V dielectric are not suitable for decoupling in this application and should **NOT** be used .

A suitable Murata capacitor would be GRM42-2X7R475K-50.



7. Inductor selection

The inductance is determined by two factors : the switching frequency and the inductor ripple Current.

The calculation of the inductance , L1 , can be described as :

L1>(VIN-VOUT-VSEN-(Rds(ON)x IOUT))x D/(fswx ΔIL)

Higher values of inductance are recommended at higher supply voltages in order to minimize errors due to switching delays, which result in increased ripple and lower efficiency. Higher values of inductance also result in a smaller change in output current over the supply voltage range. (See graphs). The inductor should be mounted as close to the device as possible with low resistance connections to the SW and VIN pins.

The chosen coil should have a saturation current higher than the peak output current and a continuous current rating above the required mean output current.

The inductor value should be chosen to maintain operating duty cycle and switch 'on'/'off' times within the specified limits over the supply voltage and load current range.

Switch on time

Ton=
$$L\Delta I/(V_{IN}-V_{LED} - Iavg(Rs + rL + Rsw))$$

TOFF=
$$L\Delta I/(V_{LED} + V_D + Iavg (R_s + rL))$$

Where

L	is the coil inductance
rL	is the coil resistance
Rs	is the current sense resistance
lavg	is the required LED current
ΔΙ	is the coil peak-peak ripple current {Internally set to 0.3 x lavg}
Vin	is the supply voltage
Vled	is the total LED forward voltage
Rsw	is the switch resistance
VD	is the diode forward voltage at the required load current

8. Diode selection

For maximum efficiency and performance, the rectifier (D1) should be a fast low capacitance Schottky diode with low reverse leakage at the maximum operating voltage and temperature.

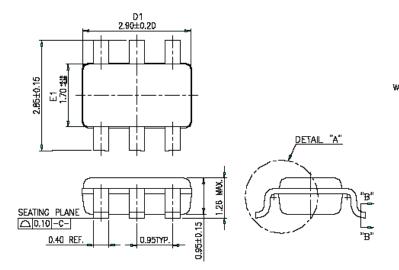
They also provide better efficiency than silicon diodes, due to a combination of lower forward voltage and reduced recovery time. It is important to select parts with a peak current rating above the peak coil current and a continuous current rating higher than the maximum output load current. It is very important to consider the reverse leakage of the diode when operating above 85°C. Excess leakage will increase the power dissipation in the device and if close to the load may create a thermal runaway condition.

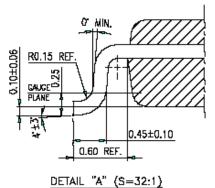
The higher forward voltage and overshoot due to reverse recovery time in silicon diodes will increase the peak voltage on the SW output. If a silicon diode is used, care should be taken to ensure that the total voltage appearing on the SW pin including supply ripple, does not exceed the specified maximum value.

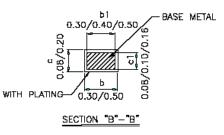


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Package Information SOT23-6 (TTP932B)



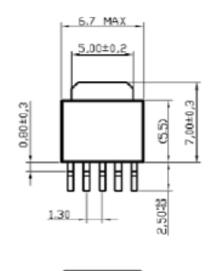


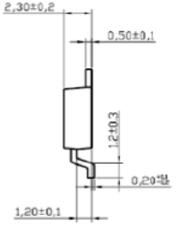


NOTES:

- 1.DIMENSION D1 & E1 DOES NOT INCLUDE MOLD PROTRUSION,
- 2.COPLANARITY OF ALL LEADS SHALL BE (BEFORE TEST) 0.1 MAX. FROM THE SEATING PLANE. UNLESS OTHERWISE SPECIFIED.
- 3.GENERAL PHYSICAL DUTLINE SPEC IS REFER TO TMC'S FINAL VISUAL INSPECTION SPEC UNLESS OTHERWISE SPECIFIED.

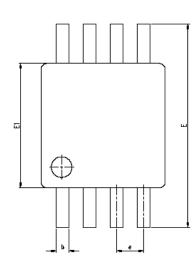
TO252-5 (TTP932C)

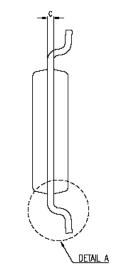






MSOP8 (TTP932D)





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<u>Detail a</u>

0.008TYP.

0.015X45*

64100	DIMENSION IN MM			DIMENSION IN INCH		
SYMBOL	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.81	1.02	1.10	0.032	0.040	D.043
A1	0.05		0.15	0.002		0.006
A2	0.76	0.86	D.95	0.030	0.034	D.037
b	0.28	0.30	D.38	0.011	0.012	D.D15
C	0.13	0.15	0.23	0.005	0.006	0.009
D	2.90	3.00	3.10	0.114	D.118	0.122
E	4.75	4.90	5.05	0.187	0.193	D.199
E1	2.90	3.00	3.10	0.114	0.118	D.122
ę	0.65 BASIC			0.0	26 BAS	IC
L	0.40	0.55	D.70	0.016	0.022	D.028
θ	Ű	3	б	Û,	3	б
JEDEC						

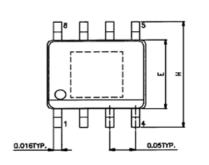
^{*}NOTES : DIMENSION " D " DOES NOT INCLUDE MOLD PROTRUSIONS OR GATE BURRS.

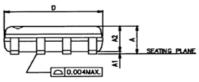
NOLD PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED

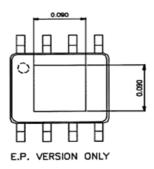
0.006 Inch (0.15 MM) PER SIDE , Dimension et does not include wold protrusions NOLD protrusions shall not exceed 0.010 Inch (0.25 MM) PER SIDE .

D.10MN C SEATING PLANE









SYMBOLS	MIN.	MAX.
A	0.053	0.069
A1	0.004	0.010
A2	-	0.059
D	0.189	0.196
E	0.150	0.157
Н	0.228	0.244
L	0.016	0.050
θ°	0	8
		UNIT : INCH

NOTES:

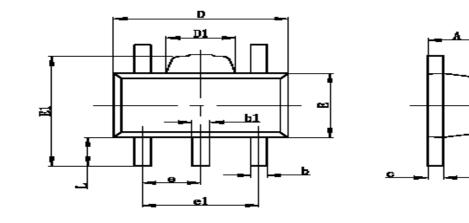
1. JEDEC OUTLINE : MS-012 M / E.P. VERSION : N/A

- 2. DIMENSIONS "D" DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED .15mm (.006in) PER SIDE.
- 3.DIMENSIONS "E" DOES NOT INCLUDE INTER-LEAD FLASH, OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED .25mm (.010in) PER SIDE.



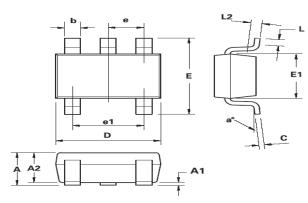
TTP932

SOT89-5 (TTP932F1)



Symbol	Dimensions	In Millimeters	Dimensions In Inches	
	Min	Max	Min	Max
A	1.400	1.600	0.055	0.063
b	0.320	0.520	0.013	0.020
b1	0.360	0.560	0.014	0.022
с	0.350	0.440	0.014	0.017
D	4.400	4.600	0.173	0.181
D1	1.400	1.800	0.055	0.071
E	2.300	2.600	0.091	0.102
E1	3.940	4.250	0.155	0.167
e	1.500TYP		0.06	OTYP
e1	2.900	3.100	0.114	0.122
L	0.900	1.100	0.035	0.043

SOT23-5 (TTP932J)



DIM	Millimeters		Inc	hes	
	Min.	Max.	Min.	Max.	
A	-	1.00	-	0.0393	
A1	0.01	0.10	0.0003	0.0039	
A2	0.84	0.90	0.0330	0.0354	
b	0.30	0.45	0.0118	0.0177	
с	0.12	0.20	0.0047	0.0078	
D	2.90	BSC	0.114 BSC		
E	2.80 BSC		0.110	BSC	
E1	1.60 BSC		0.062 BSC		
е	0.95	BSC	0.037	4 BSC	
e1	1.90 BSC		0.0748 BSC		
L	0.30	0.50	0.0118	0.0196	
L2	0.25 BSC		0.010	BSC	
a°	4 °	12°	4° 12°		